



## Material Content Data Sheet



<b>Sales Product Name</b>	SPD15P10PL G	<b>Issued</b>	30. April 2021
<b>MA#</b>	MA001726314		
<b>Package</b>	PG-TO252-3-311	<b>Weight*</b>	315.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.612	1.15	1.15	11465	11465
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	iron	7439-89-6	0.143	0.05		455	
	non noble metal	copper	7440-50-8	143.098	45.40	45.46	454149	454740
wire	non noble metal	aluminium	7429-90-5	1.335	0.42	0.42	4236	4236
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.972	0.63		6258	
	plastics	brominated resin	-	2.113	0.67		6705	
	organic material	carbon black	1333-86-4	2.254	0.72		7152	
	plastics	epoxy resin	-	19.015	6.03		60349	
	inorganic material	silicondioxide	60676-86-0	115.500	36.66	44.71	366562	447026
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11870	11870
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275
solder	non noble metal	tin	7440-31-5	0.060	0.02		189	
	noble metal	silver	7440-22-4	0.074	0.02		236	
	non noble metal	lead	7439-92-1	2.842	0.90	0.94	9021	9446
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60863	60942
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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